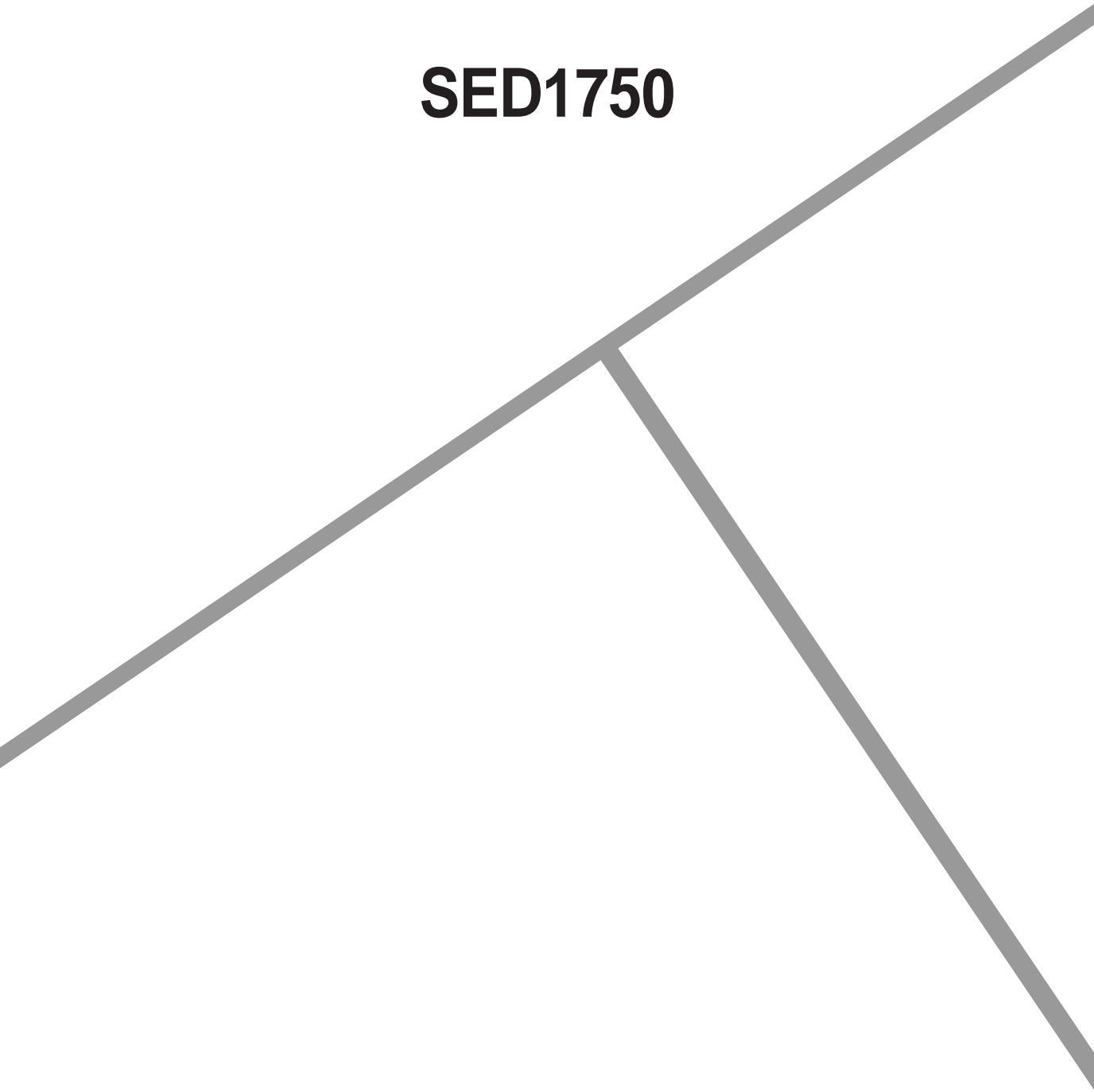


SED1750



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OVERVIEW

The SED1750 is an MLS (Multi Line Selection) driving, 160 output, triple-value low resistance common (low) driver which can realize high picture quality and high speed responses.

Receiving signals from an LCD controller such as the SED1335 or SED1351, it works to make 4-line MLS drives in combination with the SED1580 or in combination with the SED1590 receiving signals direct from the MPU. Employing the SCI7500 as the power IC, the power to use for the MLS drive liquid crystal display system can be prepared easily.

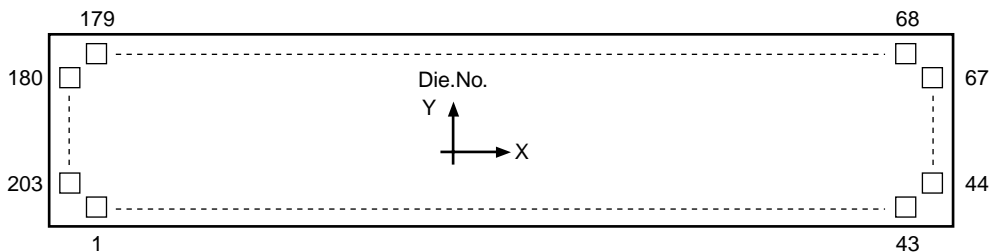
Adopting a slim chip shape which is more advantageous to realize narrower borders with the LCD panels, the SED1750 is capable of making low voltage logic power operations and is applicable to a wide range of applications.

Owing to its pad layout designed to facilitate its installation to the substrate and thanks to its two-way choices of the driver output sequence, the highest working efficiency can be acquired with a 1/160 or 1/320 duty panel.

Features

- LCD driver outputs 160
- Low output ON resistance
- High duty drive supported 1/320 (Reference value)
- Broad range of LC drive voltages + 14 to + 42 V (VCC = 2.7 to 5.5 V)
- Output shift direction pin select is possible
- Can be switched between 140 and 160 outputs
- Non-biased display OFF function
- Logic system power source 2.7 V to 5.5 V
- LC power source offset bias can be adjusted relative to the VDDH and GND levels
- Slim chip shape
- D0B Au Bump die
- T0A TCP

Pad Layout



Chip size	15.62 mm × 2.47 mm
Pad pitch	80 μm (Min.)
Chip thickness	525 μm ± 25 μm

1) Au Bump Specifications (SED1750D0B) Reference Values Only

Au vertical bump

Parallel to Scribe × Perpendicular to Scribe ± Tolerance

Bump Size A	60 μm × 75 μm ± 4 mm (Pad No. 1 to 43, 68 to 179)
Bump Size B	80 μm × 50 μm ± 4 mm (Pad No. 44 to 67, 180 to 203)
Bump height	17 to 28 μm (The details specified in the acceptance specifications.)

Pad Coordinates

Units: μm

Pin	Name	X	Y	Pin	Name	X	Y	Pin	Name	X	Y
1	V _{DDH}	-7522	-1045	51	COM8	7655	-375	101	COM58	3008.4	1083
2	+V1	-7427		52	COM9		-295	102	COM59	2874.7	
3	VC	-7332		53	COM10		-215	103	COM60	2741	
4	-V1	-7237		54	COM11		-135	104	COM61	2607.4	
5	V _{SS}	-7142		55	COM12		-55	105	COM62	2473.7	
6	SHL	-6804		56	COM13		25	106	COM63	2340	
7	SEL	-6579		57	COM14		105	107	COM64	2206.4	
8	V _{CC}	-6241		58	COM15		185	108	COM65	2072.7	
9	LSEL	-5902		59	COM16		265	109	COM66	1939	
10	DOFF	-5538		60	COM17		345	110	COM67	1805.4	
11	FR	-4791		61	COM18		425	111	COM68	1671.7	
12	DM	-4323		62	COM19		505	112	COM69	1538.1	
13	DM	-3943		63	COM20		585	113	COM70	1404.4	
14	DM	-3563		64	COM21		665	114	COM71	1270.7	
15	DM	-3183		65	COM22		745	115	COM72	1137.1	
16	DM	-2803		66	COM23		825	116	COM73	1003.4	
17	CSEL	-2336		67	COM24		905	117	COM74	869.7	
18	LP	-1998		68	COM25	7419.3	1083	118	COM75	736.1	
19	DM	-1162		69	COM26	7285.6		119	COM76	602.4	
20	CIO2	-755		70	COM27	7152		120	COM77	468.7	
21	DM	-347		71	COM28	7018.3		121	COM78	335.1	
22	DM	0		72	COM29	6884.7		122	COM79	201.4	
23	DM	347		73	COM30	6751		123	COM80	67.7	
24	CIO1	755		74	COM31	6617.3		124	COM81	-67.7	
25	DM	1162		75	COM32	6483.7		125	COM82	-201.4	
26	YD	1998		76	COM33	6350		126	COM83	-335.1	
27	DM	2336		77	COM34	6216.3		127	COM84	-468.7	
28	DM	2803		78	COM35	6082.7		128	COM85	-602.4	
29	DM	3183		79	COM36	5949		129	COM86	-736.1	
30	DM	3563		80	COM37	5815.3		130	COM87	-869.7	
31	DM	3943		81	COM38	5681.7		131	COM88	-1003.4	
32	DM	4323		82	COM39	5548		132	COM89	-1137.1	
33	DM	4791		83	COM40	5414.3		133	COM90	-1270.7	
34	DM	5538		84	COM41	5280.7		134	COM91	-1404.4	
35	F1	5902		85	COM42	5147		135	COM92	-1538.1	
36	DM	6241		86	COM43	5013.3		136	COM93	-1671.7	
37	F2	6579		87	COM44	4879.7		137	COM94	-1805.4	
38	TEST1	6804		88	COM45	4746		138	COM95	-1939	
39	V _{SS}	7142		89	COM46	4612.3		139	COM96	-2072.7	
40	-V1	7237		90	COM47	4478.7		140	COM97	-2206.4	
41	VC	7332		91	COM48	4345		141	COM98	-2340	
42	+V1	7427		92	COM49	4211.4		142	COM99	-2473.7	
43	V _{DDH}	7522		93	COM50	4077.7		143	COM100	-2607.4	
44	COM1	7655	-935	94	COM51	3944		144	COM101	-2741	
45	COM2		-855	95	COM52	3810.4		145	COM102	-2874.7	
46	COM3		-775	96	COM53	3676.7		146	COM103	-3008.4	
47	COM4		-695	97	COM54	3543		147	COM104	-3142	
48	COM5		-615	98	COM55	3409.4		148	COM105	-3275.7	
49	COM6		-535	99	COM56	3275.7		149	COM106	-3409.4	
50	COM7		-455	100	COM57	3142		150	COM107	-3543	

Pin	Name	X	Y
151	COM108	-3676.7	1083
152	COM109	-3810.4	
153	COM110	-3944	
154	COM111	-4077.7	
155	COM112	-4211.4	
156	COM113	-4345	
157	COM114	-4478.7	
158	COM115	-4612.3	
159	COM116	-4746	
160	COM117	-4879.7	
161	COM118	-5013.3	
162	COM119	-5147	
163	COM120	-5280.7	
164	COM121	-5414.3	
165	COM122	-5548	
166	COM123	-5681.7	
167	COM124	-5815.3	
168	COM125	-5949	

Pin	Name	X	Y
169	COM126	-6082.7	1083
170	COM127	-6216.3	
171	COM128	-6350	
172	COM129	-6483.7	
173	COM130	-6617.3	
174	COM131	-6751	
175	COM132	-6884.7	
176	COM133	-7018.3	
177	COM134	-7152	
178	COM135	-7285.6	
179	COM136	-7419.3	
180	COM137	-7655	905
181	COM138		825
182	COM139		745
183	COM140		665
184	COM141		585
185	COM142		505
186	COM143		425

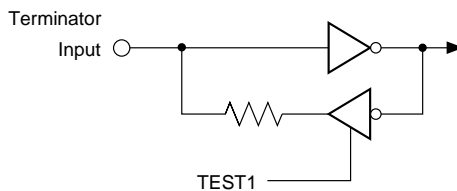
Pin	Name	X	Y
187	COM144	-7655	345
188	COM145		265
189	COM146		185
190	COM147		105
191	COM148		25
192	COM149		-55
193	COM150		-135
194	COM151		-215
195	COM152		-295
196	COM153		-375
197	COM154		-455
198	COM155		-535
199	COM156		-615
200	COM157		-695
201	COM158		-775
202	COM159		-855
203	COM160		-935

TERMINAL FUNCTIONS

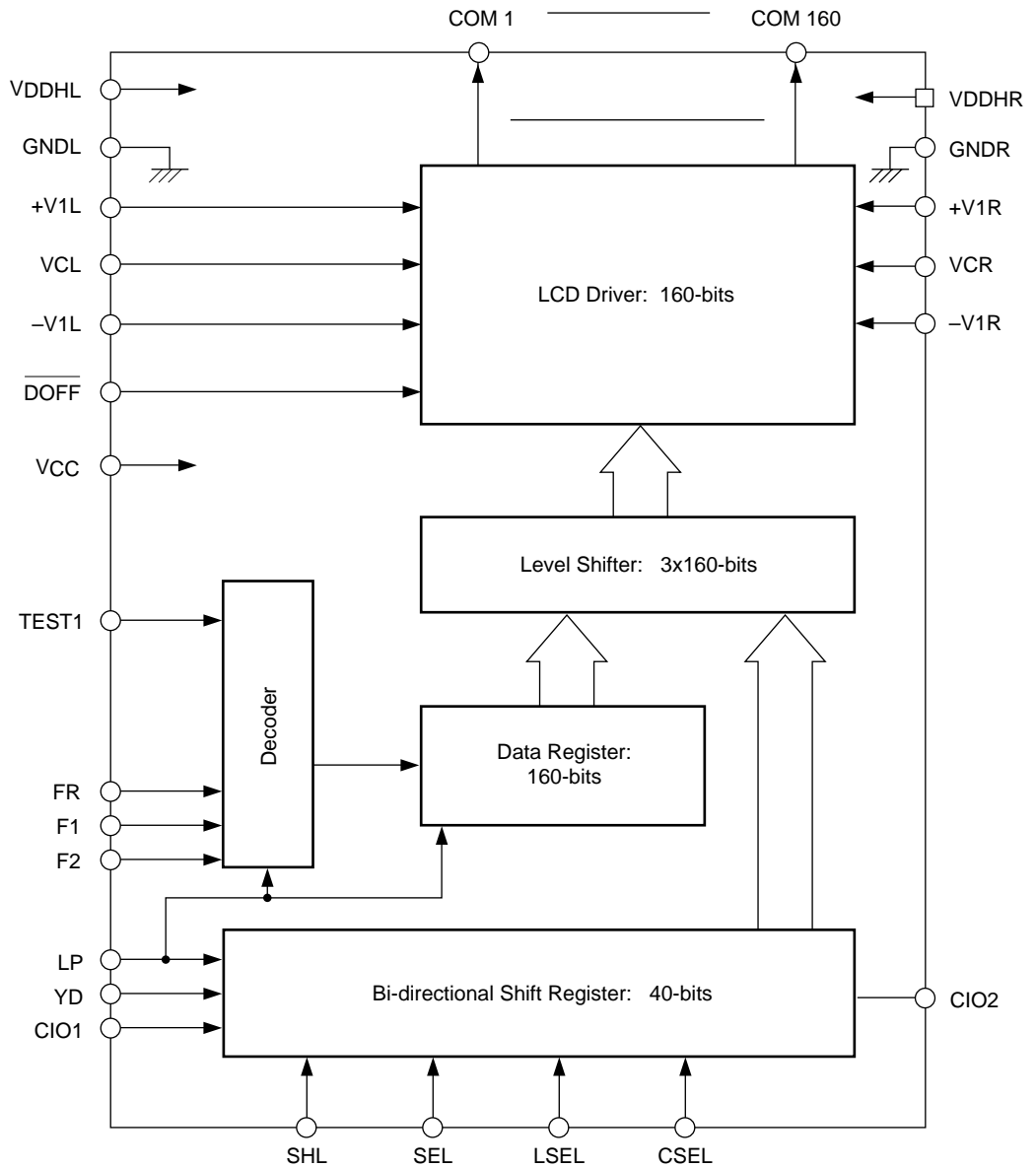
Terminal Name	I/O	Function	Number of Terminals																	
COM1 to COM160	O	Common (row) output to drive LC. Output transition occurs on falling edge of LP.	160																	
CIO1 CIO2	I/O	Carry signal I/O. This is set to input or output depending on the level of the SHL input. Output transition occurs on falling edge of LP.	2																	
YD	I	Frame start/pulse input, with terminator. (*1)	1																	
F1, F2	I	Drive pattern select signal input, with terminator. (*1)	2																	
LP	I	Shift clock input for display data. (Triggers on falling edge.) With terminator. (*1)	1																	
SHL	I	Shift direction select and CIO terminal I/O control input.	1																	
		<table border="1"> <thead> <tr> <th rowspan="2">SHL</th> <th colspan="2">Output Shift Direction</th> <th rowspan="2">CIO1</th> <th rowspan="2">CIO2</th> </tr> <tr> <th></th> <th></th> </tr> </thead> <tbody> <tr> <td>L</td> <td>1(9)</td> <td>→ 160(148)</td> <td>Input</td> <td>Output</td> </tr> <tr> <td>H</td> <td>160(148)</td> <td>→ 1(9)</td> <td>Output</td> <td>Input</td> </tr> </tbody> </table>		SHL	Output Shift Direction		CIO1	CIO2			L	1(9)	→ 160(148)	Input	Output	H	160(148)	→ 1(9)	Output	Input
		SHL			Output Shift Direction				CIO1	CIO2										
L	1(9)	→ 160(148)	Input	Output																
H	160(148)	→ 1(9)	Output	Input																
The numbers in parentheses are for 140 output mode.																				
SEL	I	Select input for the number of COM output terminals: 160 outputs ↔ 140 outputs L: COM1 to COM160 H: COM9 to COM148	1																	
LSEL	I	1/2 H operation select signal input. L: Normal operation. H: 1/2 operation.	1																	
CSEL	I	Chip select signal input for when a cascade connection is used. L: Leading chip H: Other chips	1																	
FR	I	LC drive output AC signal input. With terminator (*1)	1																	
$\overline{\text{DOFF}}$	I	LC display blanking control input. With a low level input, all common outputs are temporarily set to the Vc level. The contents of the latches are maintained. With terminator (*1)	1																	
TEST1	I	Test1 signal input. Normally tied at L.	1																	
Vcc, GNDL, GNDR	Power	Power source for logic: GND: 0 V, Vcc: +2.7 to 5.5 V	3																	
VCL, VCR, +V1L, +V1R, -V1L, -V1R, VDDHL, VDDHR	Power	LC Drive Power: GND: 0 V, VDDH: + 14.0 to 42.0 V, VDDH ≥ +V1 ≥ Vc ≥ -V1 ≥ GND	8																	
DM		Dummy pad	19																	

Total 203

Note: *1



Block Diagram



Explanation of Each Block

Shift Register

This is a bi-directional shift register used for transmitting common data. The display data shifts on the falling edge of LP.

Level Shifter

The level shifter is a voltage level converter circuit which converts the signal voltage level from a logic system level to the LC driver system voltage level.

LCD Driver

The LCD driver outputs the LC drive voltage.

The relationship between the display blanking signal $\overline{\text{DOFF}}$, the field recognition signals F1 & F2, the AC signal FR, and the common output voltage is as follows:

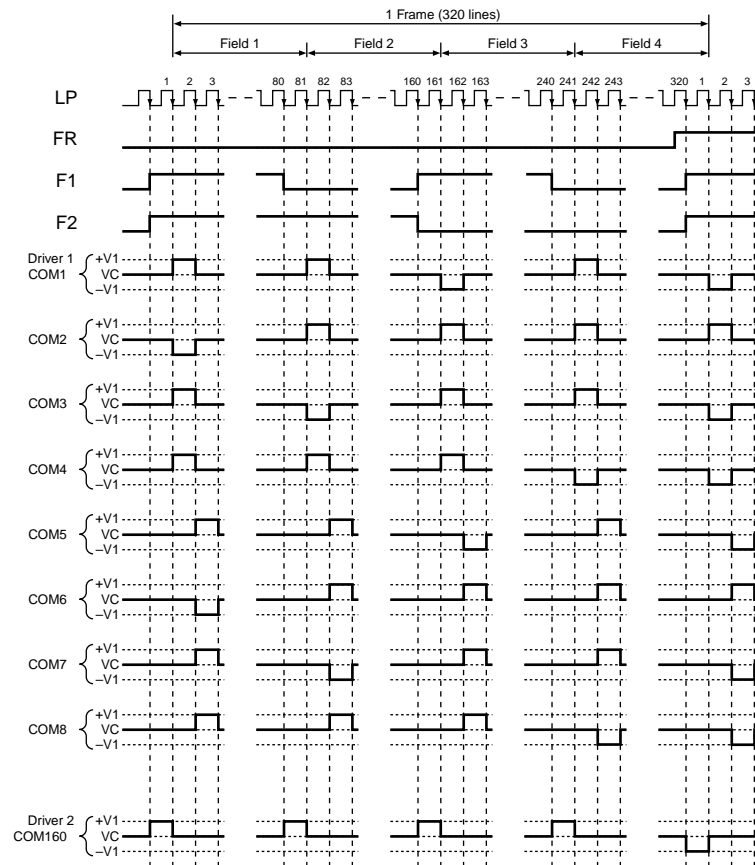
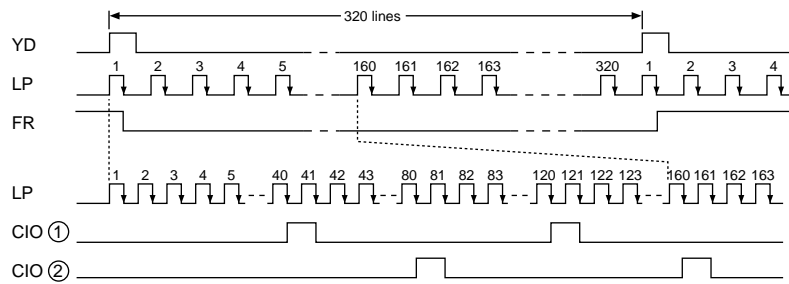
DOFF	H								L
FR	L				H				—
F1,F2	1,1	0,1	1,0	0,0	1,1	0,1	1,0	0,0	—
Line 1	+V ₁	+V ₁	-V ₁	+V ₁	-V ₁	-V ₁	+V ₁	-V ₁	V _C
Line 2	-V ₁	+V ₁	+V ₁	+V ₁	+V ₁	-V ₁	-V ₁	-V ₁	V _C
Line 3	+V ₁	-V ₁	+V ₁	+V ₁	-V ₁	+V ₁	-V ₁	-V ₁	V _C
Line 4	+V ₁	+V ₁	+V ₁	-V ₁	-V ₁	-V ₁	-V ₁	+V ₁	V _C

Voltage level relationships: + V₁ > V_C > -V₁ (V_C is the center voltage level)

Timing Diagram (1)

1/320 duty, normal operation.

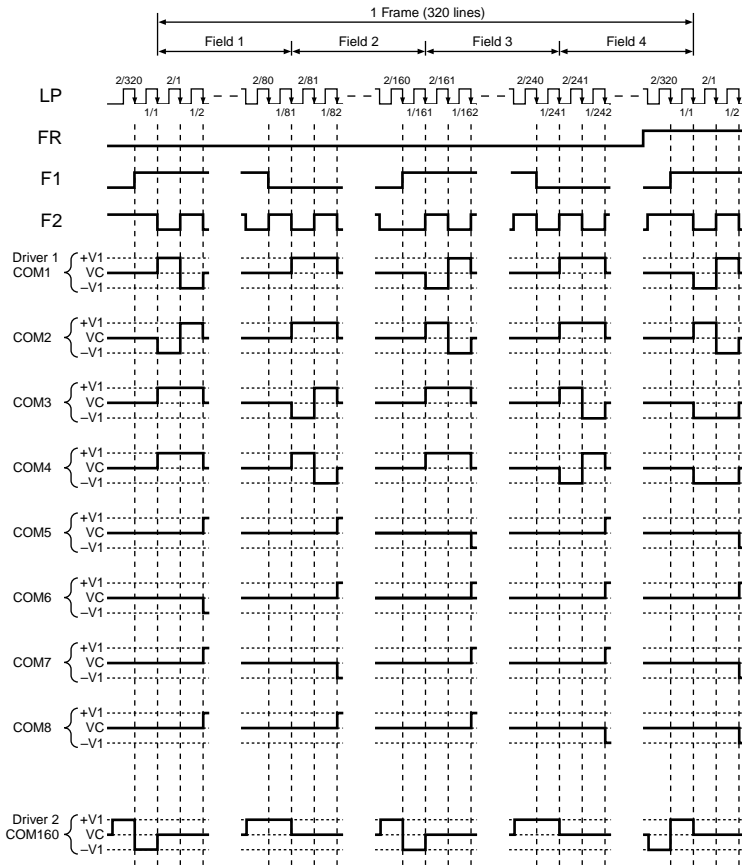
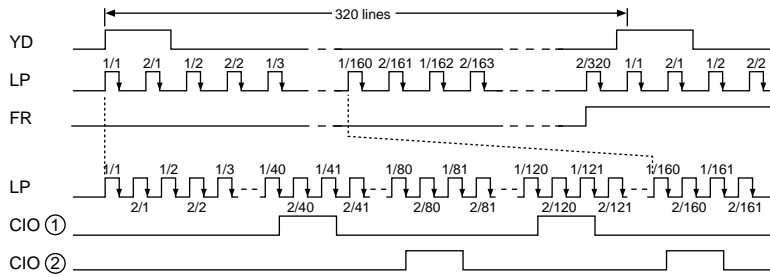
SHL = L, SEL = L, LSEL = L, CSEL = L (This diagram provided only as a reference.)



Timing Diagram (2)

1/320 duty, 1/2 H operation.

SHL = L, SEL = L, LSEL = H, CSEL = L (This diagram provided only as a reference.)



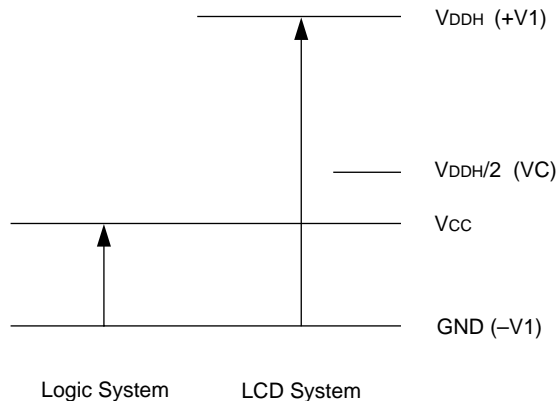
ABSOLUTE MAXIMUM RATINGS

Item	Signal	Rated Value	Units
Power voltage (1)	VCC	-0.3 to +7.0	V
Power voltage (2)	VDDH	-0.3 to + 45.0	V
Power voltage (3)	$\pm V_1, V_C$	GND - 0.3 to VDDH + 0.3	V
Input voltage	V_I	GND - 0.3 to VCC + 0.3	V
Output voltage	V_O	GND - 0.3 to VCC + 0.3	V
CIO output current	I_{O1}	20	mA
Operating temperature	T_{opr}	-30 to +85	°C
Storage temperature 1	Tstg1	-65 to +150	°C
Storage temperature 2	Tstg2	-55 to +100	°C

NOTE 1: The voltages are all relative to GND = 0 V.

NOTE 2: Storage temperature 1 is for the chip alone, and storage temperature 2 is for the TCP product.

NOTE 3: Ensure that the relationship between +V₁, V_C, and -V₁ is always as follows:
 $V_{DDH} \geq +V_1 \geq V_C \geq -V_1 \geq \text{GND}$.



NOTE 4: The LSI may be permanently damaged if the logic system power is floating or VCC is less than or equal to 2.6 V when power is applied to the LC drive system. Special caution must be paid to the power sequences during power up and power down.

Electrical Characteristics

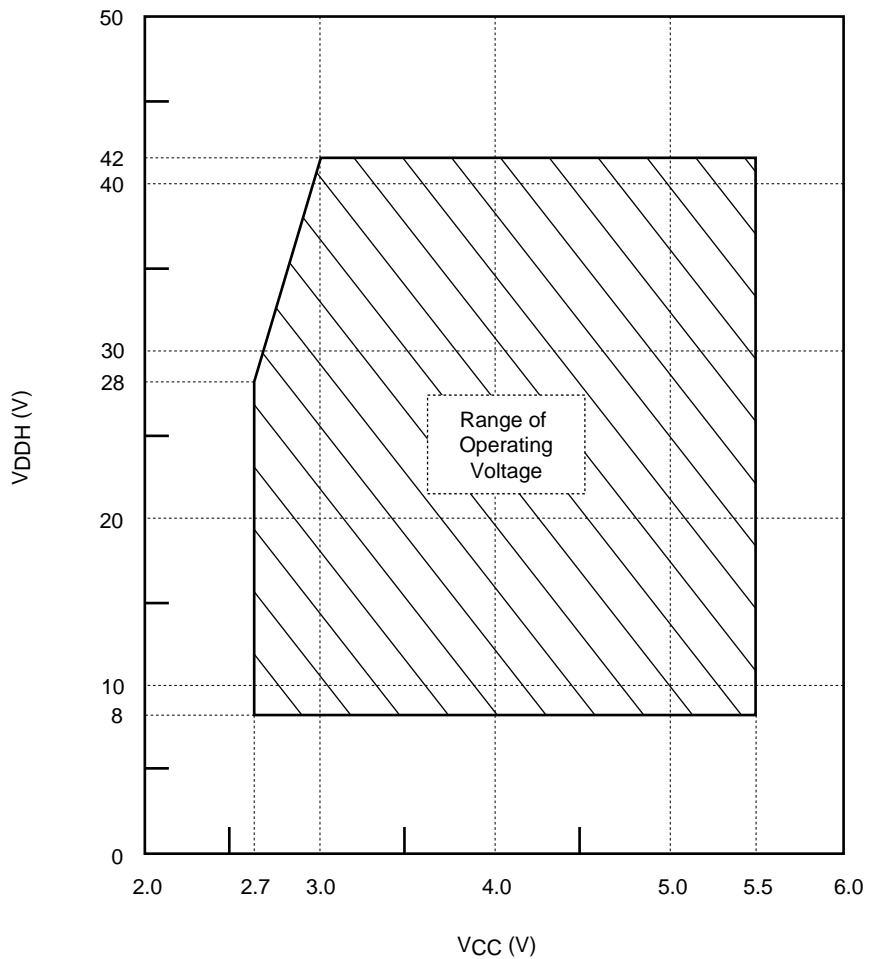
DC Characteristics

Unless otherwise noted, GND = 0 V, VCC = + 5.0 V ± 10%, Ta = -30 to 85°C

Item	Signal	Parameter	Applicable Terminals	Min	Typ	Max	Unit
Power Supply Voltage (1)	VCC		VCC	2.7	5.0	5.5	V
Range Operating Voltages	VDDH	Function	VDDH	8.0		42.0	V
Power Supply Voltage (2)	+V1	Recommended Value	+V1			VDDH	V
Power Supply Voltage (3)	Vc	Recommended Value	Vc		VDDH/2		V
Power Supply Voltage (4)	-V1	Recommended Value	-V1	GND			V
High-level Input Voltage	VIH	VCC = 2.7 to 5.5V	CIO1,CIO2,FR, YD,LP,SHL,SEL, LSEL,CSEL,F1, DOFF,F1,F2, TEST1	0.8VCC			V
Low-level Input Voltage	VIL					0.2VCC	V
High-level Output Voltage	VOH	VCC = 2.7 to 5.5V	CIO1,CIO2	VCC-0.4			V
Low-level Output Voltage	VOL				IOH = -0.3mA	IOL = 0.3mA	
Input Leakage Current	II	GND ≤ VIN ≤ VCC	LP,YD,SHL,SEL, LSEL,CSEL,F1, F2,DOFF,TEST1, FR			2.0	μA
Input/Output Leakage Current	II/O	GND ≤ VIN ≤ VCC	CIO1,CIO2			5.0	μA
Static Current	IGND	VDDH = 14.0~42.0V VIH = VCC, VIL = GND	GND			25	μA
Output Resistance	R _{COM}	ΔV _{ON} = 0.5 V Recommended parameter	COM1 to COM120		0.55	0.7	kΩ
					0.5	0.7	
Average Operating Consumption Current (1)	I _{CC}	VCC = +5.0 V, VIH = VCC VIL = GND, f _{LP} = 22.4 kHz f _{FR} = 70 Hz, Input data: 1/320 No load	VCC		12	25	μA
		VCC = 3.0 V All other parameters the same as VCC = 5.0 V.			8	17	
Average Operating Consumption Current (2)	I _{DDH}	VDDH = +V1 = +30.0 V, Vc = VDDH/2, -V1 = 0.0 V, VCC = 5.0 V All other parameters the same as the I _{CC} item.	VDDH		7	13	μA
Input Terminal Capacity	CI	Freq. = 1 MHz Chip alone	LP,YD,SHL,SEL, LSEL,CSEL,F1,F2, DOFF,TEST1,FR			10	pF
Input/Output Terminal Capacity	C _{I/O}	Ta = 25°C	CIO1,CIO2			18	pF

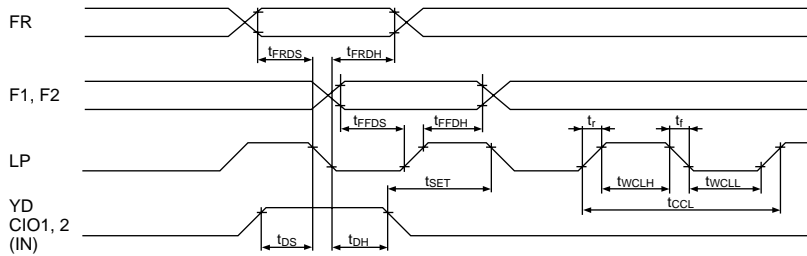
Range of Operating Voltages: $V_{CC} - V_{DDH}$

It is necessary to set the voltage for V_{DDH} within the $V_{CC} - V_{DDH}$ operating voltage range shown in the diagram below.



AC Characteristics

Input Timing Characteristics



The FR latched at the nth LP is reflected in the output at the n+1th LP.

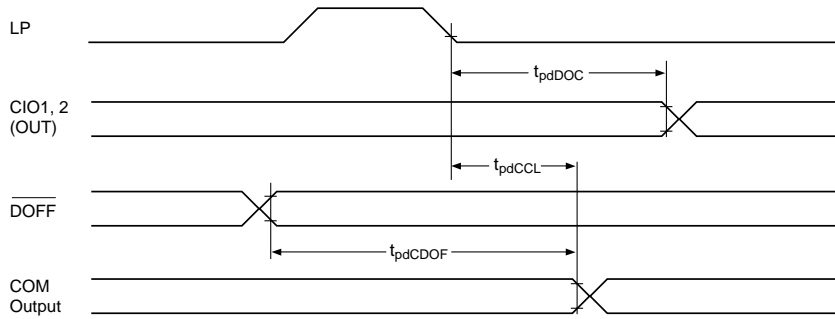
($V_{CC} = +5.0\text{ V} \pm 10\%$, $T_a = -30$ to $+85^\circ\text{C}$)

Item	Signal	Parameter	Min	Max	Units
LP Frequency	t_{CCL}		500		ns
LP "H" Pulse Width	t_{WCLH}		55		ns
LP "L" Pulse Width	t_{WCLL}		330		ns
FR Setup Time	t_{FRDS}		100		ns
FR Hold Time	t_{FRDH}		40		
F1, F2 Setup Time	t_{FFDS}		100		
F1, F2 Hold Time	t_{FFDH}		40		
Input Signal Rise Time	t_r			50	ns
Input Signal Fall Time	t_f			50	ns
CIO Setup Time	t_{DS}		100		ns
CIO Hold Time	t_{DH}		40		ns
YD → LP Allowable Time	t_{SET}		80		ns

($V_{CC} = +2.7\text{ V}$ to 4.5 V , $T_a = -30$ to $+85^\circ\text{C}$)

Item	Signal	Parameter	Min	Max	Units
LP Frequency	t_{CCL}		800		ns
LP "H" Pulse Width	t_{WCLH}		100		ns
LP "L" Pulse Width	t_{WCLL}		660		ns
FR Setup Time	t_{FRDS}		200		ns
FR Hold Time	t_{FRDH}		40		
F1, F2 Setup Time	t_{FFDS}		200		
F1, F2 Hold Time	t_{FFDH}		40		
Input Signal Rise Time	t_r			100	ns
Input Signal Fall Time	t_f			100	ns
CIO Setup Time	t_{DS}		200		ns
CIO Hold Time	t_{DH}		40		ns
YD → LP Allowable Time	t_{SET}		150		ns

Output Timing Characteristics



($V_{CC} = 5.0\text{ V} \pm 10\%$, $V_{DDH} = +14.0$ to $+42.0\text{ V}$, $T_a = -30$ to $+85^\circ\text{C}$)

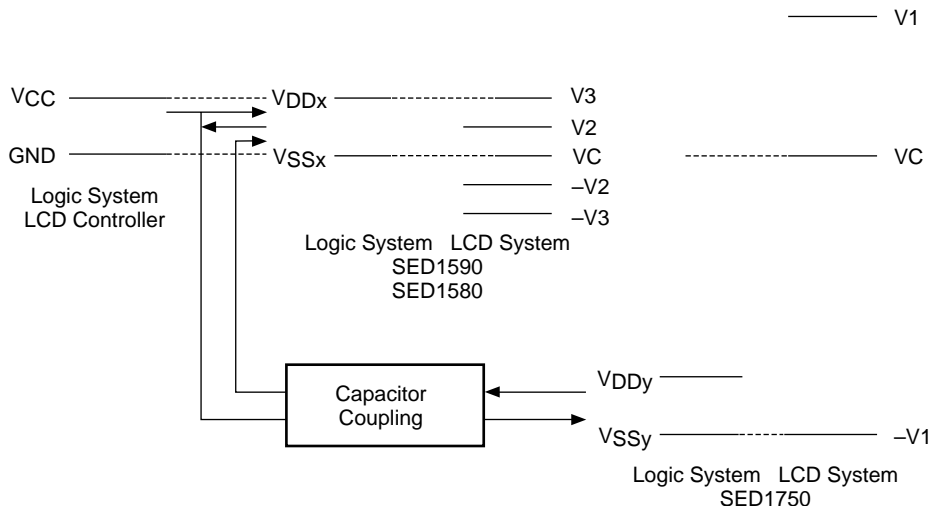
Item	Signal	Parameter	Min	Max	Units
Delay time from LP to CIO output	t_{pdDOC}	$C_L = 15\text{ pF}$ $V_{DDH} = 14.0\text{ V to }40.0\text{ V}$		300	ns
Delay time from LP to COM output	t_{pdCCL}			350	ns
Delay time from \overline{DOFF} to COM output	t_{pdCDOF}			700	ns

($V_{CC} = +2.7\text{ V to }4.5\text{ V}$, $V_{DDH} = +14.0$ to $+28.0\text{ V}$, $T_a = -30$ to $+85^\circ\text{C}$)

Item	Signal	Parameter	Min	Max	Units
Delay time from LP to CIO output	t_{pdDOC}	$C_L = 15\text{ pF}$ $V_{DDH} = 14.0\text{ V to }40.0\text{ V}$		600	ns
Delay time from LP to COM output	t_{pdCCL}			500	ns
Delay time from \overline{DOFF} to COM output	t_{pdCDOF}			1400	ns

The Power Supply

Method of Forming Each Voltage Level



When the SED1590 (SED1580) and the SED1750 are used to form an extremely low power module system, the power relationships as shown in the figure above between the SED1590 (SED1580) and SED1750 logic systems, and the LCD system power supply, and the LCD controller power supply are optimal.

In this case, care is required when it comes to signal propagation in the logic system.

LCD Controller	→	SED1580, SED1590	Direct
LCD Controller	→	SED1750	Capacitor coupling is required
SED1580, SED1590	→	SED1750	Capacitor coupling is required
SED1750	→	SED1580, SED1590	Capacitor coupling is required

Cautions at Power Up and Power Down

Because the voltage level in the LCD system is high voltage, if the logic system power supply of this LSI is floating or if VCC is 2.6 V or less when the LCD system high voltage (30 V or above) is applied, or if the LCD drive signal is output before the voltage level that is applied to the LCD system has stabilized, then there is the risk that there will be an over current condition in this LSI, resulting in permanent damage to this LSI.

It is recommended that the display OFF function (DOFF) is used until the LCD system voltage stabilizes to insure that the LCD drive output power level is at the VC level.

Be sure to follow the sequences below when turning the power supplies ON and OFF:

When turning the power supply ON:

Logic system ON → LCD drive system ON, or simultaneously ON.

When turning the power supply OFF:

LCD drive system OFF → Logic system OFF, or simultaneously OFF.

As a countermeasure to guard against over current conditions, it is effective to insert a high-speed fuse or a guard resistance in series with the LC power supply. The guard resistance value must be optimized depending on the capacity of the LC cell.

Example of Connection

